

DESCRIPTION

The BSS123L is available in SOT-23 package

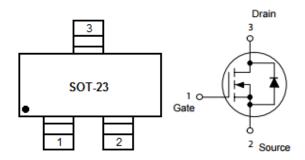
FEATURES

Available in SOT-23 package

ORDERING INFORMATION

Package Type	Part Number				
SOT-23	BSS123L				
Note SPQ: 3,000pcs/Reel					
AiT provides all RoHS Compliant Products					

PIN DESCRIPTION



ABSOLUTE MAXIMUM RATINGS

V _{DSS} , Drain–Source Voltage	100Vdc
V _{GS} , Gate–Source Voltage– Continuous	±20Vdc
V _{GSM} , Gate–Source Voltage– Non–repetitive (tp ≤ 50 µs)	±40Vpk
I _D , Drain Current Continuous NOTE1	0.17Adc
I _{DM} , Drain Current Pulsed NOTE2	0.68Adc

Stresses above may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated in the Electrical Characteristics are not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

THERMAL CHARACTERISTICS

Parameter	Symbol	Max	Unit
Total Device Dissipation FR–5 Board NOTE3			
T _A = 25°C	P _D	225	mW
Derate above 25°C		1.8	mW/°C
Thermal Resistance, Junction to Ambient	R _{0JA}	556	°C/W
Junction and Storage Temperature	TJ, TSTG	-55 to +150	°C

NOTE1: The Power Dissipation of the package may result in a lower continuous drain current.

NOTE2: Pulse Width ≤300µs, Duty Cycle ≤ 2.0%.

NOTE3: $FR-5 = 1.0 \times 0.75 \times 0.062$ in.

REV1.0 - JUL 2015 RELEASED - -1

ELECTRICAL CHARACTERISTICS

T_A = 25°C, unless otherwise noted

Parameter	Symbol	Conditions		Min.	Тур.	Max.	Unit
OFF CHARACTERISTICS							
Drain–Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0, I _D = 250µAdc		100	-	-	Vdc
Zero Gate Voltage Drain		V _{GS} = 0, T _J = 25°C		-	-	15	
Current	I _{DSS}	V _{DS} = 100Vdc	T _J = 125°C	-	-	60	μAdc
Gate-Body Leakage Current	Igss	V _{GS} = 20Vdc, V _{DS} = 0		-	-	50	nAdc
ON CHARACTERISTICS NOTE4							
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{DS} = V_{GS}$, $I_D = 1.0$ mAdc		0.8	-	2.0	Vdc
Static Drain–Source	D	V _{GS} = 10Vdc, I _D = 100mAdc		-	F 0	6.0	0
On–Resistance	R _{DS(on)}				5.0	6.0	Ω
Forward Transconductance	g fs	V_{DS} = 25Vdc, I_D = 100mAdc		80	1	1	mmhos
DYNAMIC CHARACTERISTICS							
Input Capacitance	Ciss	V _{DS} = 25Vdc, V _{GS} = 0, f = 1.0 MHz		-	20	1	pF
Output Capacitance	C_{oss}	V _{DS} = 25Vdc, V _{GS} = 0, f = 1.0 MHz		-	9.0	-	pF
Reverse Transfer	(C _{rss} V _{DS} = 25Vdc, V _{GS} = 0, f = 1.0 MHz			4.0		5.F
Capacitance	Orss			-	4.0		pF
SWITCHING CHARACTERISTICS NOTE4							
Turn-On Delay Time	$t_{\text{d(on)}}$	V _{CC} = 30Vdc, I _C = 0.28Adc,		-	20	-	ns
Turn-Off Delay Time	$t_{\text{d(off)}}$	V_{GS} = 10Vdc, R_{GS} = 50 Ω			40	ı	ns
REVERSE DIODE							
Diode Forward On-Voltage	V _{SD}	$I_D = 0.34$ Adc, $V_{GS} = 0$ Vdc		-	-	1.3	V

NOTE4: Pulse Test: Pulse Width≤300µs, Duty Cycle≤2.0%.

REV1.0 - JUL 2015 RELEASED - - 2 -

TYPICAL CHARACTERISTICS

Figure 1. Ohmic Region

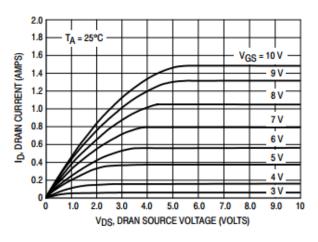


Figure 3. Temperature vs. Static Drain–Source On–Resistance

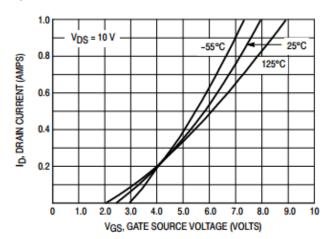
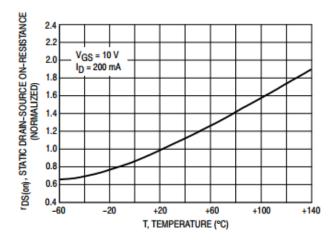
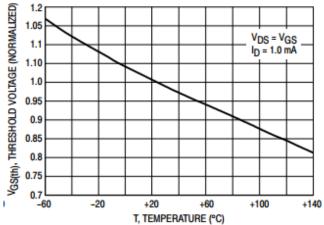


Figure 2. Transfer Characteristics

Figure 4. Temperature vs. Gate Threshold Voltage

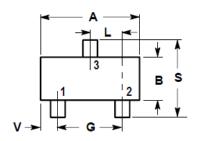


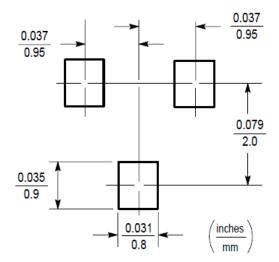


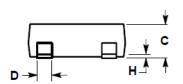
REV1.0 - JUL 2015 RELEASED - - 3 -

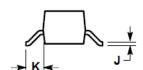
PACKAGE INFORMATION

Dimension in SOT-23 Package (Unit: mm)









DIM	MILLIMETERS		INCHES		
DIM	MIN	MAX	MIN	MAX	
А	2.80	3.04	0.1102	0.1197	
В	1.20	1.40	0.0472	0.0551	
С	0.89	1.11	0.0350	0.0440	
D	0.37	0.50	0.0150	0.0200	
G	1.78	2.04	0.0701	0.0807	
Н	0.013	0.100	0.0005	0.0040	
J	0.085	0.177	0.0034	0.0070	
K	0.35	0.69	0.0140	0.0285	
L	0.89	1.02	0.0350	0.0401	
S	2.10	2.64	0.0830	0.1039	
V	0.45	0.60	0.0177	0.0236	

REV1.0 - JUL 2015 RELEASED - - 4 -



IMPORTANT NOTICE

AiT Semiconductor Inc. (AiT) reserves the right to make changes to any its product, specifications, to discontinue any integrated circuit product or service without notice, and advises its customers to obtain the latest version of relevant information to verify, before placing orders, that the information being relied on is current.

AiT Semiconductor Inc.'s integrated circuit products are not designed, intended, authorized, or warranted to be suitable for use in life support applications, devices or systems or other critical applications. Use of AiT products in such applications is understood to be fully at the risk of the customer. As used herein may involve potential risks of death, personal injury, or servere property, or environmental damage. In order to minimize risks associated with the customer's applications, the customer should provide adequate design and operating safeguards.

AiT Semiconductor Inc. assumes to no liability to customer product design or application support. AiT warrants the performance of its products of the specifications applicable at the time of sale.

REV1.0 - JUL 2015 RELEASED - - 5 -